

IEEE EPS as Speakers in IMPACT Taiwan

Oct 22-25th, 2024



IMPACT 2024
#S17 SPIL- ADVANCED PACKAGING

- **MING-YI TSAI, PROFESSOR, CHANG GUNG UNIVERSITY**
How to Characterize Bending Strength of Thin Dies
- **EU POH LENG, SENIOR DIRECTOR, NXP**
PLP Advanced Packaging Global Overview
- **CARL CHEN, DEPUTY TECHNICAL DIRECTOR, SPIL**
IC Substrate Development Trend and Future Holds
- **GEORGE LIN, SENIOR DIRECTOR, INNOLUX CORPORATION**
How Innolux can groundbreak advanced IC package
- **FUSAO TAKAGI, MANAGER, RDL Embedded Coreless Substrate**

Date
Oct. 24 (THUR.)



- IMPACT 2024 was organized by IEEE-EPS-Taipei, iMAPS-Taiwan, ITRI, and TPCA. This year's event was held from Oct. 22nd-25th at Taipei Nangang Exhibition Center, in conjunction with TPCA Show 2024. The symposium focused on the theme "IMPACT on Sustainable Technology", exploring the latest electronic technologies and fostering collaboration among enterprises and organizations.
- IEEE EPS Malaysia committee Dr Eu and Miss Sze Pei were honored to be invited as speakers. Dr Eu shared "PLP Advanced Packaging Global Overview" and Miss Sze Pei shared "Innovative Interconnect Material for Advanced Packaging Assembly Process". Event was well supported by > 700 participants.

